

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



re application of:

TONGBI JIANG
EDWARD SCHROCK

Serial No.: 09/258,961

ART UNIT: 2811

Filing Date: 03/01/1999

Examiner: PAREKH, NITIN

Title: BGA PACKAGE HAVING SUBSTRATE
WITH PATTERNED SOLDER MASK
DEFINING OPEN DIE ATTACH AREA
(AS AMENDED)

Attorney Docket No.: 98-0645.1

**AMENDMENT SUBMITTED WITH REQUEST FOR CONTINUED
EXAMINATION (RCE) UNDER 37 CFR 1.114**

March 26, 2004

Mail Stop RCE
Commissioner For Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

This Amendment is in response to the final Office Action dated 11/28/2003, having a statutory period for response set to expire on 03/01/2004, but extended for thirty days by the enclosed Petition For Extension Of Time until 04/01/2004. Please amend the case as follows.

03/30/2004 EAREGAY1 00000049 071857 09258961

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